UNISONIC TECHNOLOGIES CO., LTD

UT2N15 POWER MOSFET

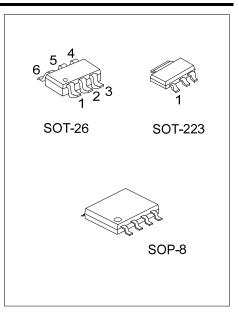
2.0A, 150V N-CHANNEL **POWER MOSFET**

DESCRIPTION

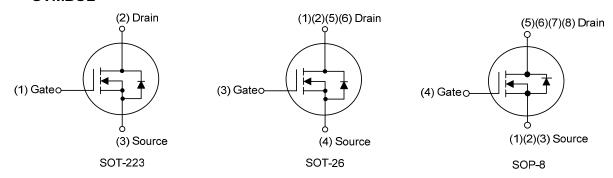
The UTC UT2N15 is a high voltage power MOSFET combines advanced trench MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications of switching power supplies and adaptors.

FEATURES

- * $R_{DS(ON)} \le 0.3 \Omega @ V_{GS} = 10V, I_D = 1.0A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness



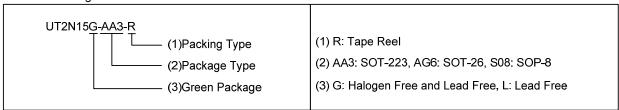
SYMBOL



ORDERING INFORMATION

Ordering Number		Daakana	Pin Assignment							Daaldaa	
Lead Free	Halogen Free	Package	1	2	3	4	5	6	7	8	Packing
UT2N15L-AA3-R	UT2N15G-AA3-R	SOT-223	G	D	ഗ	-	-	-	-	-	Tape Reel
UT2N15L-AG6-R	UT2N15G-AG6-R	SOT-26	D	Δ	G	S	D	D	-	-	Tape Reel
UT2N15L-S08-R	UT2N15G-S08-R	SOP-8	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ MARKING

PACKAGE	MARKING					
SOT-223	UT2N15 ☐ L: Lead Free → G: Halogen Free → Date Code					
SOT-26	6 5 4					
SOP-8	B 7 6 5 UTC DDD Date Code L: Lead Free UT2N15 D G: Halogen Free Lot Code					

UT2N15 Power MOSFET

■ **ABSOLUTE MAXIMUM RATING** (T_A=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	150	V
Gate-Source Voltage		V_{GSS}	±20	V
	Continuous	I_D	2	Α
Drain Current	Pulsed	I _{DM}	4	А
Avalanche Energy	rgy Single Pulsed (Note 4)		1.2	mJ
Peak Diode Recovery dv/dt (Note 5)		dv/dt	1.2	V/ns
	SOT-223		1.2	W
Power Dissipation (Note 3)	SOT-26	P_{D}	0.4	W
	SOP-8		1	W
Junction Temperature		TJ	+150	°C
Storage Temperature Range		T _{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. Surface mounted on 1 in² copper pad of FR-4 board. 270°C/W when mounted on minimum copper pad.
- 4. L=0.1mH, I_{AS} =4.8A, V_{DD} =20V, R_{G} =25 Ω , Starting T_{J} = 25°C
- 5. $I_{SD} \le 1.5A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT	
	SOT-223		104	°C/W	
Junction to Ambient	SOT-26	θ_{JA}	350	°C/W	
	SOP-8		125	°C/W	

Note: Surface mounted on 1 in² copper pad of FR-4 board. 270°C/W when mounted on minimum copper pad.

UT2N15

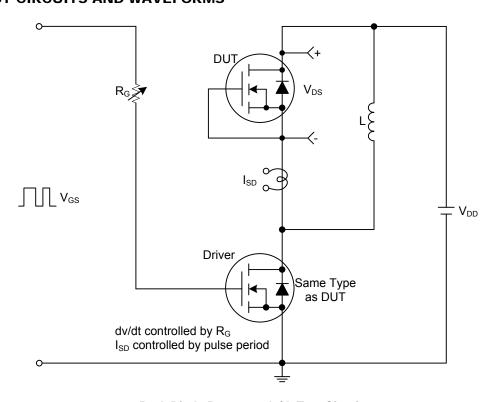
■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV_{DSS}	I _D =250μA, V _{GS} =0V	150			V		
Drain-Source Leakage Current	I _{DSS}	V _{DS} =150V, V _{GS} =0V			10	μΑ		
Gate-Source Leakage Current	Forward	I_{GSS}	V _{GS} =+20V, V _{DS} =0V			+100	nA	
	Reverse		V _{GS} =-20V, V _{DS} =0V			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	2.0		4.0	V		
Static Drain-Source On-State Resist	tance	R _{DS(ON)}	V _{GS} =10V, I _D =1.0A			0.3	Ω	
DYNAMIC PARAMETERS								
Input Capacitance		C _{ISS}			400		pF	
Output Capacitance		Coss	V_{GS} =0V, V_{DS} =25V, f=1.0MHz		40		pF	
Reverse Transfer Capacitance		C_{RSS}			22		pF	
SWITCHING PARAMETERS								
Total Gate Charge (Note 1)	Q_G	V _{DS} =120V, V _{GS} =10V, I _D =2.0A		14		nC		
Gate to Source Charge		Q_GS	$V_{DS} = 120V$, $V_{GS} = 10V$, $I_D = 2.0A$		3		nC	
Gate to Drain Charge		Q_{GD}	(1006 1, 2)		1.4		nC	
Turn-on Delay Time (Note 1)		$t_{D(ON)}$			6		ns	
Rise Time		t_R	V_{DD} =100V, V_{GS} =10V, I_{D} =2.0A,		18		ns	
Turn-off Delay Time		$t_{D(OFF)}$	$R_G = 25\Omega$ (Note 1, 2)		33		ns	
Fall-Time		t_{F}			24		ns	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous C	Is				2	Α		
Maximum Body-Diode Pulsed Curre	I _{SM}				4	Α		
Drain-Source Diode Forward Voltag	V_{SD}	I _S =2.0A, V _{GS} =0V			1.0	V		
Reverse Recovery Time		t _{rr}	I _S =2.0A, V _{GS} =0V,		54		ns	
Reverse Recovery Charge	Q_{rr}	d _{IF} /d _t =100A/μs		188		nC		

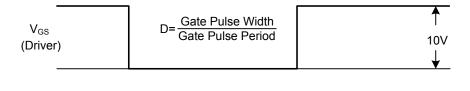
Notes: 1. Pulse Test : Pulse width \leq 300 μ s, Duty cycle \leq 2%.

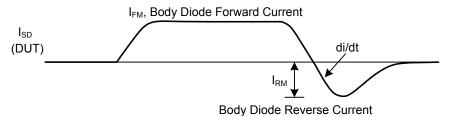
^{2.} Essentially independent of operating temperature.

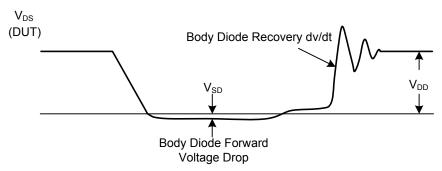
■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit



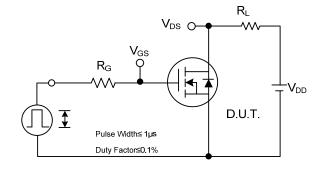


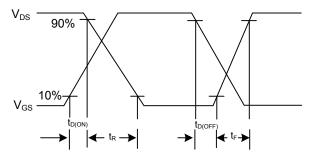


Peak Diode Recovery dv/dt Test Circuit and Waveforms

Peak Diode Recovery dv/dt Waveforms

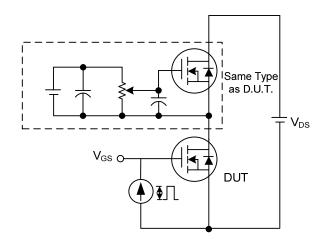
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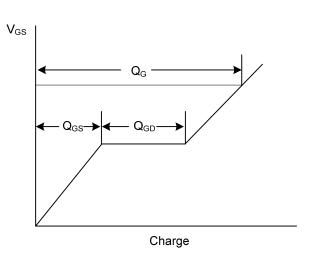




Switching Test Circuit

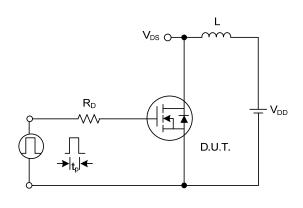
Switching Waveforms

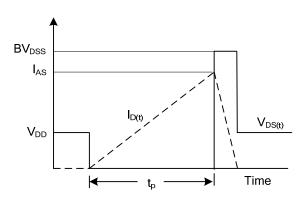




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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